



Material Content Data Sheet



Sales Product Name		BSP 62 H6327		Issued		19. July 2018		
MA#		MA001211936						
Package		PG-SOT223-4-24		Weight*		107.18 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.011	0.01		105	
	non noble metal	tin	7440-31-5	0.003	0.00		27	
	inorganic material	silicon	7440-21-3	0.137	0.13	0.14	1278	1410
leadframe	inorganic material	silicon	7440-21-3	0.009	0.01		80	
	non noble metal	titanium	7440-32-6	0.043	0.04		398	
	non noble metal	chromium	7440-47-3	0.128	0.12		1193	
	non noble metal	copper	7440-50-8	42.459	39.61	39.78	396141	397812
wire	non noble metal	copper	7440-50-8	0.082	0.08	0.08	766	766
encapsulation	organic material	carbon black	1333-86-4	0.624	0.58		5817	
	plastics	epoxy resin	-	9.353	8.73		87261	
	inorganic material	silicondioxide	60676-86-0	52.375	48.86	58.17	488660	581738
leadfinish	non noble metal	tin	7440-31-5	1.464	1.37	1.37	13659	13659
plating	noble metal	silver	7440-22-4	0.495	0.46	0.46	4615	4615
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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